

What is claimed is:

1. A noise eliminating system on chip, comprising:
 - a chip; and
 - at least one noise eliminating system built in on a surface of the chip.

5

2. The noise eliminating system on chip as claimed in claim 1 wherein the noise eliminating system is a de-coupling capacitor.

3. A noise eliminating system on chip, comprising:

10 a chip; and
 at least one noise eliminating system built in on a surface of the chip;
 wherein the noise eliminating system has two terminals which are electrically connected to guiding devices on the upper layer of the chip and are electrically connected to power supply unit and grounding unit of the chip respectively.

15

4. A noise eliminating system on chip, comprising:

10 a chip; and
 at least one noise eliminating system built in on a surface of the chip;
 wherein the two terminals of the noise eliminating system are electrically connected
20 to an additional guiding device on the chip and are connected to respective power supply
 and grounding.

5. The noise eliminating system on chip as claimed in claim 4 wherein the additional
 guiding device on the chip is a redistribution layer.

25